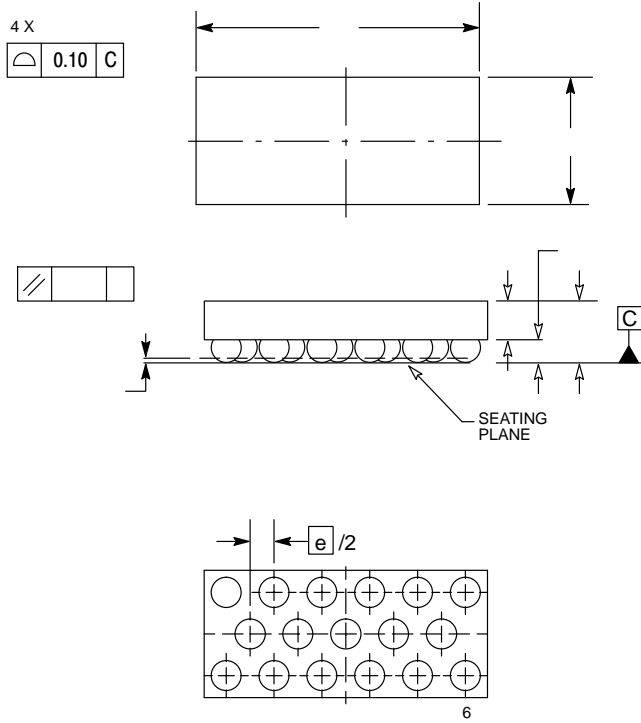


FLIP CHIP i17 CSP
CASE 499AD i01
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A1



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	iii	0.740
A1	0.250	0.310
A2	0.380	0.430
D	2.960 BSC	
E	1.330 BSC	
b	0.350	0.410
e	0.500 BSC	
e1	0.435 BSC	
D1	2.500 BSC	
E1	0.870 BSC	

GENERIC
MARKING DIAGRAM*

